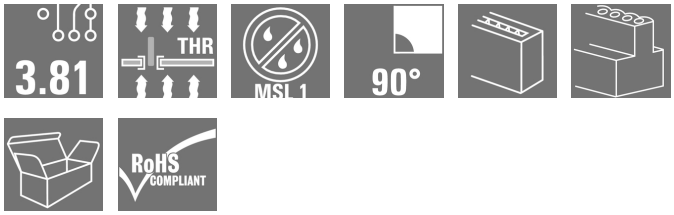
BCL-SMT 3.81/05/90 2.1SN BK BX

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

Product image



The inverted BCL-SMT socket block for the PCB offers three significant advantages:
- The BCL-SMT offers touch-safe security on the PCB which makes it ideal for live, current-carrying outputs.
- The BCL-SMT widens the range of applications with board-to-board connections between component assemblies.
- The BCL-SMT is reflow-compatible and can be seamlessly integrated into the automatic assembly and soldering process.

Two outlet directions give you a choice of position and thus more design flexibility.
- 180° standing
- 90° recumbent

Two housing variants are available for the BCL-SMT:
- Without flange
- With inverted solder flange ("LFI", with nut)
- • Fastened to PCB without additional screw
  • Fastened with screw to the SCZ FI

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of customary connectors and offer space for labelling and coding.

General ordering data

Version	PCB plug-in connector, female header, closed side, THT/THR solder connection, 3.81 mm, 90°, Solder pin length (l): 1.5 mm, tinned, black, Box
Order No.	2463340000
Type	BCL-SMT 3.81/05/90 2.1SN BK BX
GTIN (EAN)	4050118478051
Qty.	50 pc(s).
Product data	IEC: 320 V / 17.5 A UL: 300 V / 10 A
Packaging	Box

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Technical data

Dimensions and weights

Net weight	2.28 g

System specifications

Product family	OMNIMATE Signal - series BC/SC 3.81	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.81 mm
Pitch in inches (P)	0.15 inch	Outgoing elbow	90°
Number of solder pins per pole	2	Solder pin length (l)	1.5 mm
Solder pin length tolerance	0 / -0,02 mm	Solder pin dimensions	d = 0.8 mm
Solder pin dimensions = d tolerance	+0,05 / -0,05 mm	Solder eyelet hole diameter (D)	1.2 mm
Solder eyelet hole diameter tolerance (D)	+ 0,1 mm	Outside diameter of solder pad	1.9 mm
Template aperture diameter	1.6 mm	L1 in mm	15.24 mm
L1 in inches	0.6 inch	Touch-safe protection acc. to DIN VDE 57 106	Safe from finger touch
Touch-safe protection acc. to DIN VDE 0470	IP 20	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	9.5 N
Pulling force/pole, max.	6 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	120 °C	Temperature range, installation, min.	-25 °C
Temperature range, installation, max.	120 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	17.5 A
Rated current, max. number of poles (Tu=20°C)	15.4 A	Rated current, min. number of poles (Tu=40°C)	17.5 A
Rated current, max. number of poles (Tu=40°C)	13.7 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 76 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group C / CSA)	50 V
Rated current (Use group B / CSA)	11 A	Rated current (Use group C / CSA)	11 A

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Technical data

Rated data acc. to UL 1059

Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	10 A	Rated current (Use group D / UL 1059)	10 A

Packing

Packaging	Box	VPE length	125 mm
VPE width	107 mm	VPE height	24 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01		

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

ROHS	Conform

Downloads

Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN FL DRIVES DE

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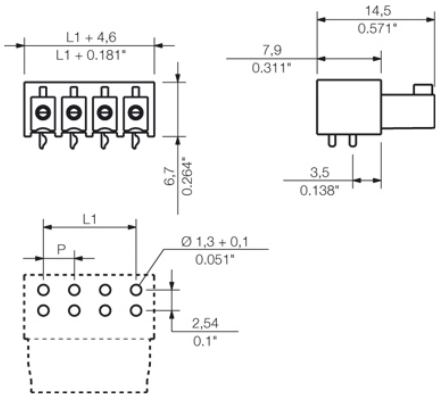
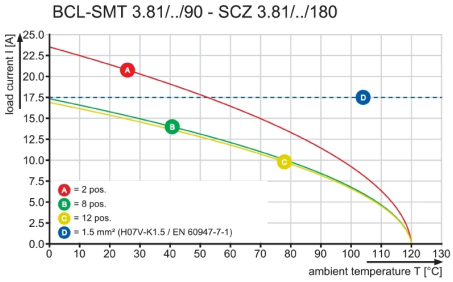
Drawings

Product image

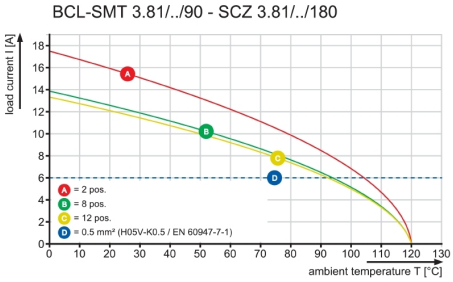
Dimensional drawing



Graph



Graph



Wave Solder Profile

Recommended wave solderding profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
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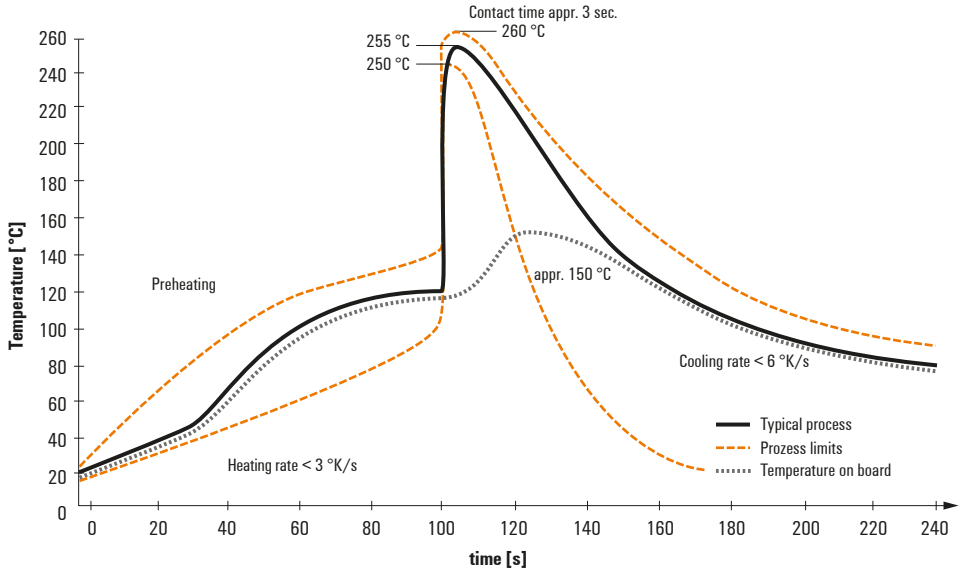
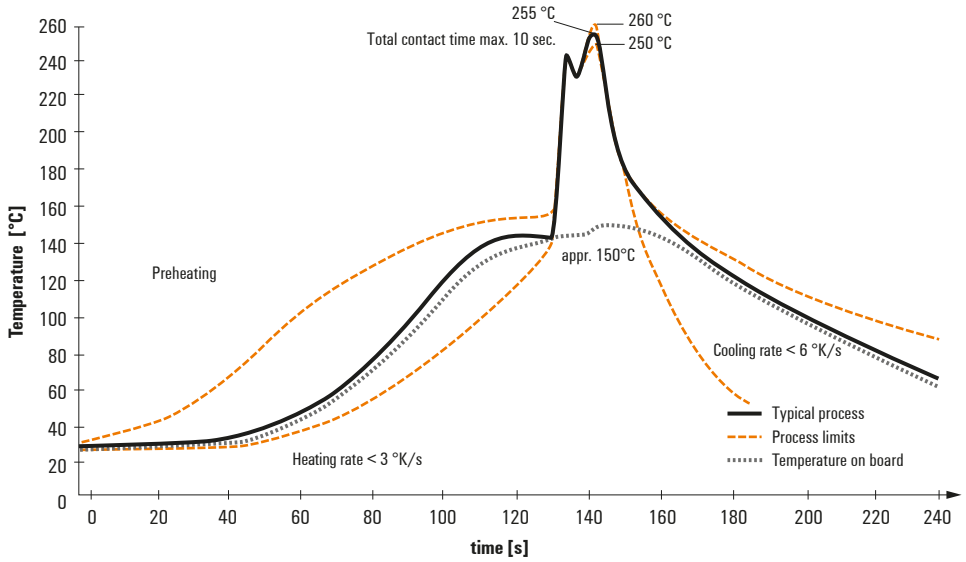
Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile

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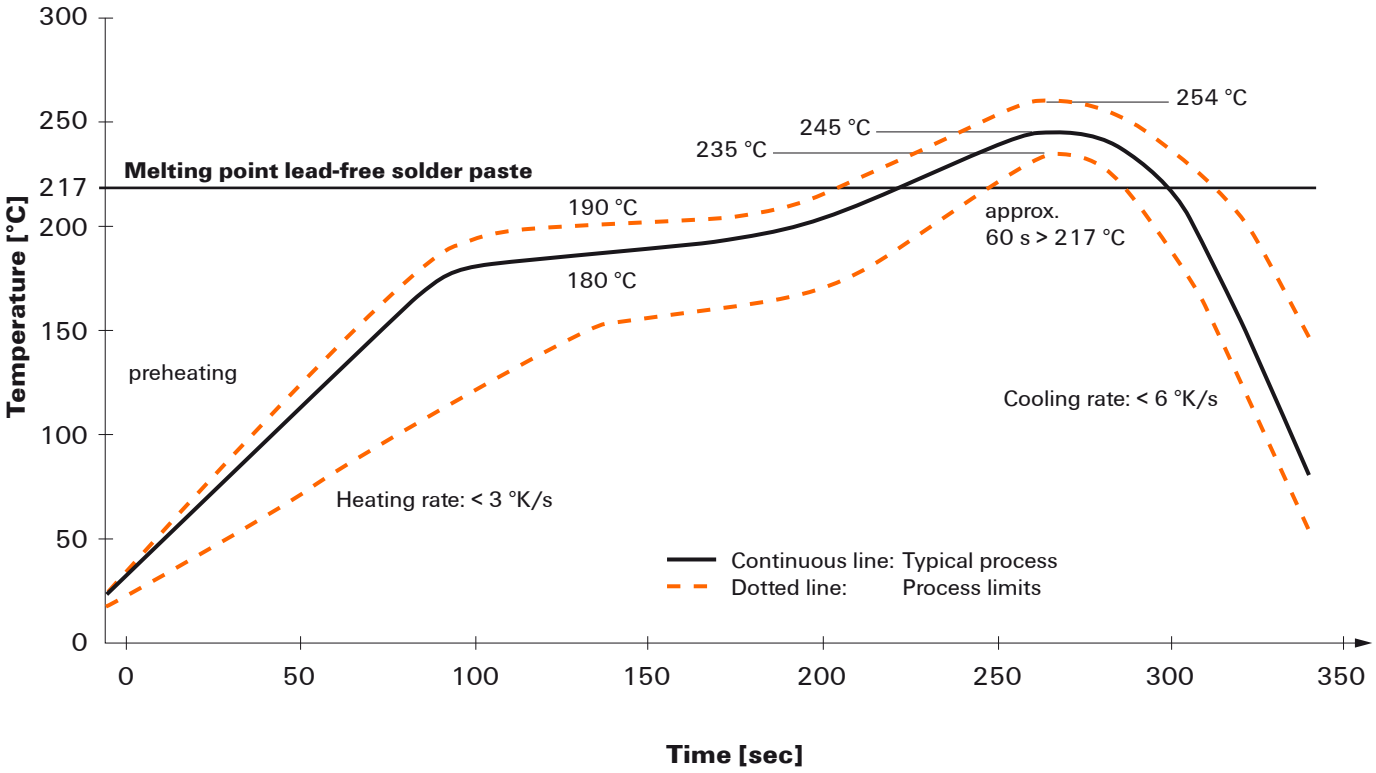

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.